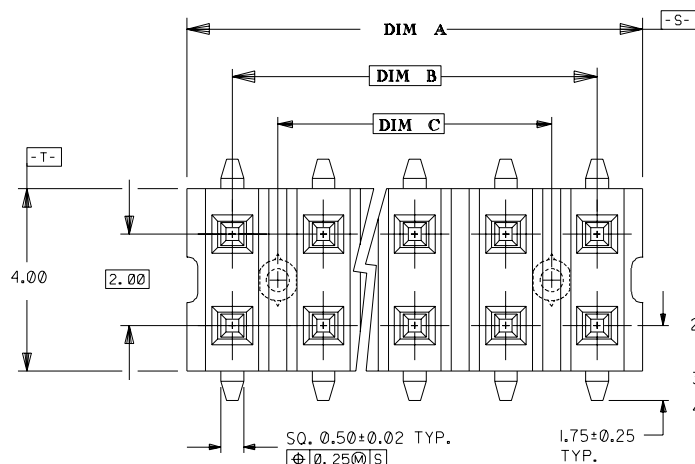
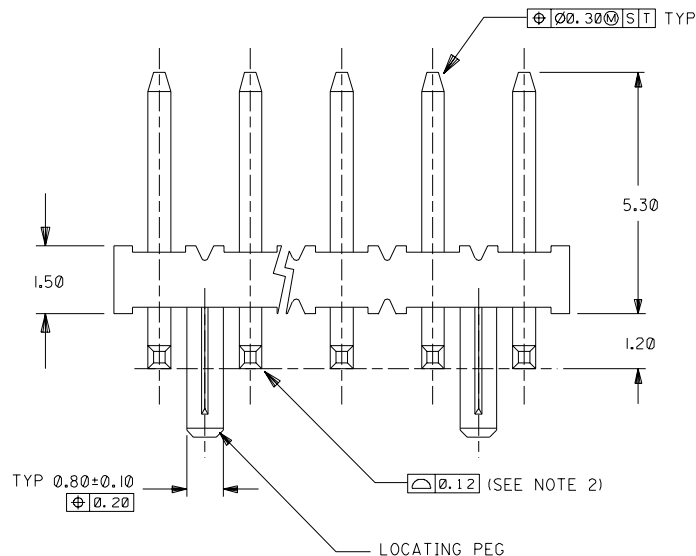




NOTES:

1. PLATING FINISH :
- 0 - 0.38um/15u" MIN. GOLD IN CONTACT AREA
1.90um/75u" MIN. TIN/LEAD
IN SOLDER TAIL AREA BOTH OVER
1.27um/50u" MIN. NICKEL OVERALL
 - 1 - 0.76um/30u" MIN. GOLD IN CONTACT AREA
1.90um/75u" MIN. TIN/LEAD
IN SOLDER TAIL AREA BOTH OVER
1.27um/50u" MIN. NICKEL OVERALL
2. COPLANARITY IS TO BE MEASURED BY RESTING THE SOLDER TAIL ON A GAUGE SURFACE.
3. PRODUCT SPECIFICATION PS-87049 APPLIES.
4. RECOMMENDED PC BOARD THICKNESS IS
1.60 ± 0.10mm.



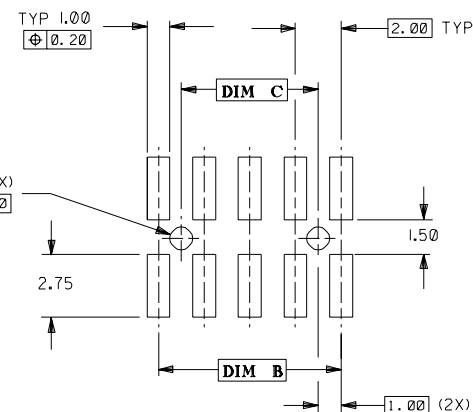
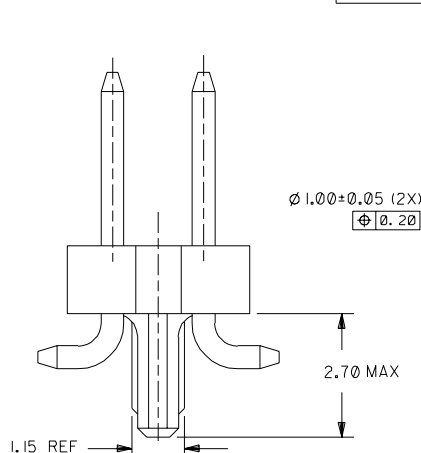
PART NUMBER LEGEND

87267 - * * 5 *

CKT SIZE

PLATING

⁰ (SEE NOTE 1)



RECOMMENDED PCB PATTERN

(SCALE 5 : 1)

C4	CHG COPLANAR FROM 0.15 TO 0.12. (ECN# S1999-0469)	-	SEE	990604	MATERIAL : HOUSING : HIGH TEMP. NYLON, 94V-0 COLOR - BALCK PIN : 0.5MM SQ. PHOSPHOR BRONZE 510	 MOLEX SINGAPORE PTE LTD SHEET 1 OF 1
C3	CHG 1.15x0.10 TO 1.15 REF (B4)	S70290	SEE	961212		
C2	REVISED PER ECN*	S40411	JACK TAY	930709	FINISH : SEE NOTE 1	GENERAL TOLERANCES $\pm 0.20/0.008$ REV C4 DWG. NO. : SD 187267--50
C1	REVISED PER ECN*	S30411	WENG TAY	930224		
C	REVISED PER ECN*	S30046	JACK TAY	920610	DRAWN BY MAX LAI 920323 CK'D BY G.W. ANG 920324	TITLE : "MILLI-GRID" 2mm DUAL ROW SMT HEADER (WITH PEG)
B	RTM PER ECN*	S2523	MAX ANG	920506		
A	REL TO TOOLING PER ECN*	S2456	MAX ANG	920323	APPR'D BY R. WONG 920324	
LTR	REVISION RECORD	ECN	DR	CHK	DATE	
REVISE ONLY ON CAD SYSTEM						